



# Product Change Notification

**Change Notification #:** 115579 - 00  
**Change Title:** Select Intel® Edison Compute Module, Intel® Edison Breakout Board, Intel® Edison Kit for Arduino\*, and Intel® Edison Breakout Board Kit Products, PCN 115579-00, Product Discontinuance, End of Life  
**Date of Publication:** June 16, 2017

## Key Characteristics of the Change:

Product Discontinuance

## Forecasted Key Milestones:

<b>Product Discontinuance Program Support Begins:</b>	June 16, 2017
<b>Product Discontinuance Demand To Local Intel Representative:</b>	July 16, 2017
<b>Last Product Discontinuance Order Date:</b>	September 16, 2017
<b>Orders are Non-Cancelable and Non-Returnable After:</b>	September 16, 2017
<b>Last Product Discontinuance Shipment Date:</b>	December 16, 2017

## Description of Change to the Customer:

Intel Corporation will discontinue manufacturing and selling all skus of the Intel® Edison compute modules and developer kits. Shipment of all Intel® Edison product skus ordered before the last order date will continue to be available from Intel until December 16, 2017.

Last time orders (LTO) for any Intel® Edison products must be placed with Intel by September 16, 2017.

All orders placed with Intel for Intel® Edison products are non-cancelable and non-returnable after September 16, 2017.

## Customer Impact of Change and Recommended Action:

The products listed on the "Products Affected/Intel Ordering Codes" table should be managed in accordance to the "Key Milestones" listed above. Supply is limited and will be committed out to orders as a "first come, first serve" basis until supply is depleted.

Please contact your local Intel Field Sales representative if you have any further questions about this End of Life notice.

\*Other names and brands may be claimed as the property of others.

## Products Affected / Intel Ordering Codes:

Product Name	Product Code	MM#
Intel® Edison Compute Module (IoT, On-Board Antenna)	EDI2.SPON.AL.S	939910
Intel® Edison Compute Module (IoT, Off-Board Antenna)	EDI2.SPOF.AL.S	939957
Intel® Edison Compute Module (IoT Wearable, On-Board Antenna)	EDI2.LPON.AL.S	939962
Intel® Edison Kit for Arduino*, Single	EDI2ARDUIN.AL.K	939976
Intel® Edison Breakout Board Kit, Single	EDI2BB.AL.K	939977
Intel® Edison Compute Module (IoT, On-Board Antenna) 10 Pack	EDI2.SPON.AL.MP	939978
Intel® Edison Compute Module (IoT, On-Board Antenna) 10 Pack	EDI2.SPON.D.MP	952661
Intel® Edison Compute Module (IoT, Off-Board Antenna) 10 Pack	EDI2.SPOF.AL.MP	939983
Intel® Edison Compute Module (IoT Wearable, On-Board Antenna) 10 Pack	EDI2.LPON.AL.MP	939985
Intel® Edison Breakout Board, Single	BB2.AL.B	939992
Intel® Edison Kit for Arduino*, Std Power, On-Board Antenna, Single	EDI3ARDUIN.AL.K	939997
Intel® Edison Breakout Board Kit, Std Power, On-Board Antenna, Single	EDI3BB.AL.K	939998

## PCN Revision History:

**Date of Revision:**

June 16, 2017

**Revision Number:**

00

**Reason:**

Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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